

Quad 2-Input Data Selector/Multiplexer with 3-State Outputs

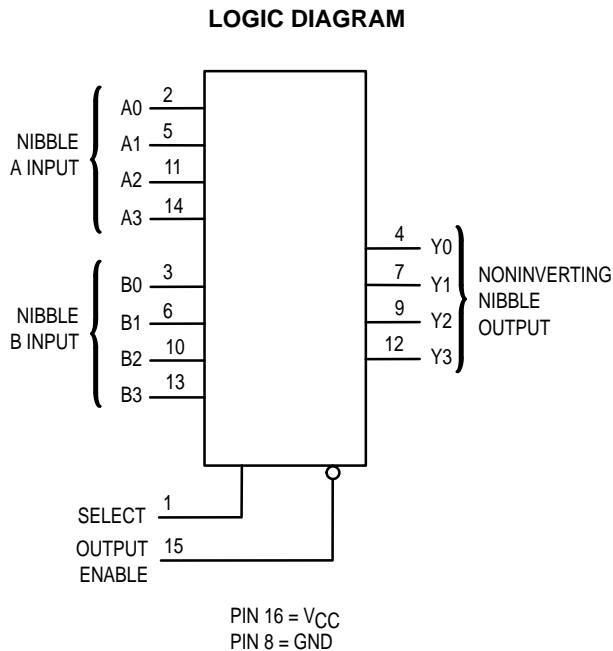
High-Performance Silicon-Gate CMOS

The MC74HC257 is identical in pinout to the LS257. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

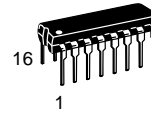
This device selects a (4-bit) nibble from either the A or B inputs as determined by the Select input. The nibble is presented at the outputs in noninverted form when the Output Enable pin is at a low level. A high level on the Output Enable pin switches the outputs into the high-impedance state.

The HC257 is similar in function to the HC157 which do not have 3-state outputs.

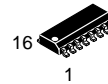
- Output Drive Capability: 15 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 108 FETs or 27 Equivalent Gates



MC74HC257



N SUFFIX
PLASTIC PACKAGE
CASE 648-08

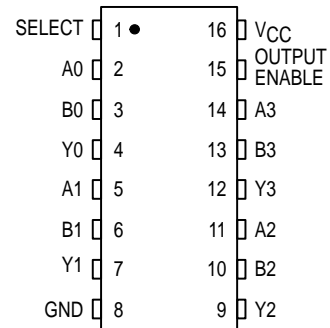


D SUFFIX
SOIC PACKAGE
CASE 751B-05

ORDERING INFORMATION

MC74HCXXXN Plastic
MC74HCXXXD SOIC

PIN ASSIGNMENT



FUNCTION TABLE

Inputs		Outputs
Output Enable	Select	Y0 - Y3
H	X	Z
L	L	A0 - A3
L	H	B0 - B3

X = don't care

Z = high impedance

A0 - A3, B0 - B3 = the levels of the respective Nibble Inputs.



MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit	
V_{CC}	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V	
V_{in}	DC Input Voltage (Referenced to GND)	- 1.5 to $V_{CC} + 1.5$	V	
V_{out}	DC Output Voltage (Referenced to GND)	- 0.5 to $V_{CC} + 0.5$	V	
I_{in}	DC Input Current, per Pin	± 20	mA	
I_{out}	DC Output Current, per Pin	± 35	mA	
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 75	mA	
P_D	Power Dissipation in Still Air	Plastic DIP† SOIC Package†	750 500	mW
T_{stg}	Storage Temperature	- 65 to + 150	°C	
T_L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C	

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $GND \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

* Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

† Derating — Plastic DIP: - 10 mW/°C from 65° to 125°C
SOIC Package: - 7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V	
T_A	Operating Temperature, All Package Types	- 55	+ 125	°C	
t_r, t_f	Input Rise and Fall Time (Figure 1)	$V_{CC} = 2.0 \text{ V}$ $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$	0 0 0	1000 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit			Unit
				- 55 to 25°C	$\leq 85^\circ\text{C}$	$\leq 125^\circ\text{C}$	
V_{IH}	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \leq 20 \mu\text{A}$	2.0	1.5	1.5	1.5	V
			4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
V_{IL}	Maximum Low-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \leq 20 \mu\text{A}$	2.0	0.3	0.3	0.3	V
			4.5	0.9	0.9	0.9	
			6.0	1.2	1.2	1.2	
V_{OH}	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 20 \mu\text{A}$	2.0	1.9	1.9	1.9	V
			4.5	4.4	4.4	4.4	
		$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 6.0 \text{ mA}$ $ I_{out} \leq 7.8 \text{ mA}$	4.5	3.98	3.84	3.70	
			6.0	5.48	5.34	5.20	
V_{OL}	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 20 \mu\text{A}$	2.0	0.1	0.1	0.1	V
			4.5	0.1	0.1	0.1	
		$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 6.0 \text{ mA}$ $ I_{out} \leq 7.8 \text{ mA}$	4.5	0.26	0.33	0.40	
			6.0	0.26	0.33	0.40	
I_{in}	Maximum Input Leakage Current	$V_{in} = V_{CC} \text{ or } GND$	6.0	± 0.1	± 1.0	± 1.0	μA
I_{OZ}	Maximum Three-State Leakage Current	Output in High-Impedance State $V_{in} = V_{IL} \text{ or } V_{IH}$ $V_{out} = V_{CC} \text{ or } GND$	6.0	± 0.5	± 5.0	± 10	μA
I_{CC}	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC} \text{ or } GND$ $I_{out} = 0 \mu\text{A}$	6.0	8	80	160	μA

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

AC ELECTRICAL CHARACTERISTICS ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			- 55 to 25°C	≤ 85°C	≤ 125°C	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Nibble A or B to Output Y (Figures 1 and 4)	2.0	100	125	150	ns
		4.5	20	25	30	
		6.0	17	21	26	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Select to Output Y (Figures 2 and 4)	2.0	100	125	150	ns
		4.5	20	25	30	
		6.0	17	21	26	
t _{PLZ} , t _{PHZ}	Maximum Propagation Delay, Output Enable to Output Y (Figures 3 and 5)	2.0	150	190	225	ns
		4.5	30	38	45	
		6.0	26	33	38	
t _{PZL} , t _{PZH}	Maximum Propagation Delay, Output Enable to Output Y (Figures 3 and 5)	2.0	150	190	225	ns
		4.5	30	38	45	
		6.0	26	33	38	
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 4)	2.0	60	75	90	ns
		4.5	12	15	18	
		6.0	10	13	15	
C _{in}	Maximum Input Capacitance	—	10	10	10	pF
C _{out}	Maximum Three-State Output Capacitance (Output in High-Impedance State)	—	15	15	15	pF

NOTES:

- For propagation delays with loads other than 50 pF, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).
- Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

C _{PD}	Power Dissipation Capacitance (Per Package)*	Typical @ 25°C, V _{CC} = 5.0 V	pF
		39	

* Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$. For load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

PIN DESCRIPTIONS**INPUTS****A0, A1, A2, A3 (Pins 2, 5, 11, 14)**

Nibble A input. The data present on these pins is transferred to the output when the Select input is at a low level and the Output Enable input is at a low level. The data is presented to the outputs in noninverted form.

B0, B1, B2, B3 (Pins 3, 6, 10, 13)

Nibble B input. The logic data present on these pins is transferred to the output when the Select input is at a high level and the Output Enable input is at a low level. The data is presented to the outputs in noninverted form.

OUTPUTS**Y0, Y1, Y2, Y3 (Pins 4, 7, 9, 12)**

Nibble output. The selected nibble input is presented at these outputs when the Output Enable input is at a low level.

For the Output Enable input at a high level, the outputs are switched to the high impedance state.

CONTROL INPUTS**Select (Pin 1)**

Nibble select. This input determines the nibble to be transferred to the outputs. A low level on this input selects the A inputs and a high level selects the B inputs.

Output Enable (Pin 15)

Output Enable. A low level on this input allows the selected input data to be presented at the outputs. A high level on this input forces the outputs into the high-impedance state.

SWITCHING WAVEFORMS

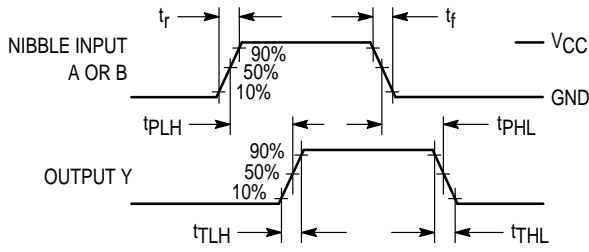


Figure 1.

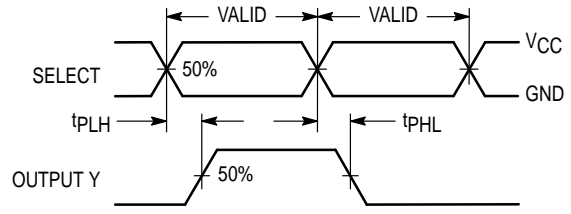


Figure 2.

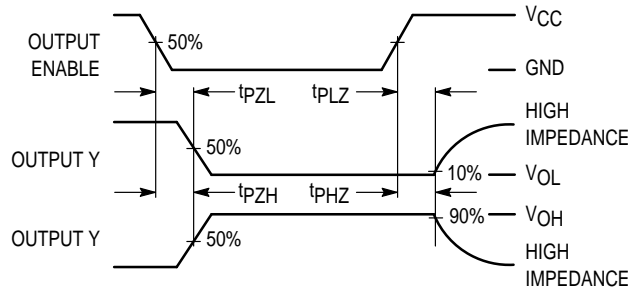
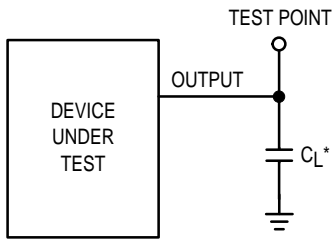


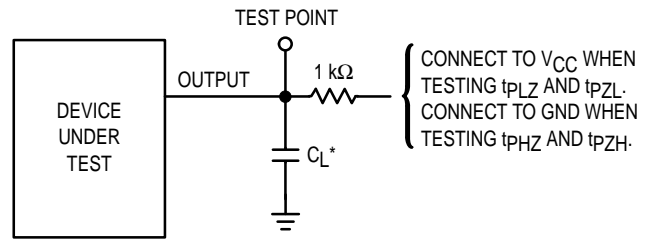
Figure 3.

TEST CIRCUITS



* Includes all probe and jig capacitance

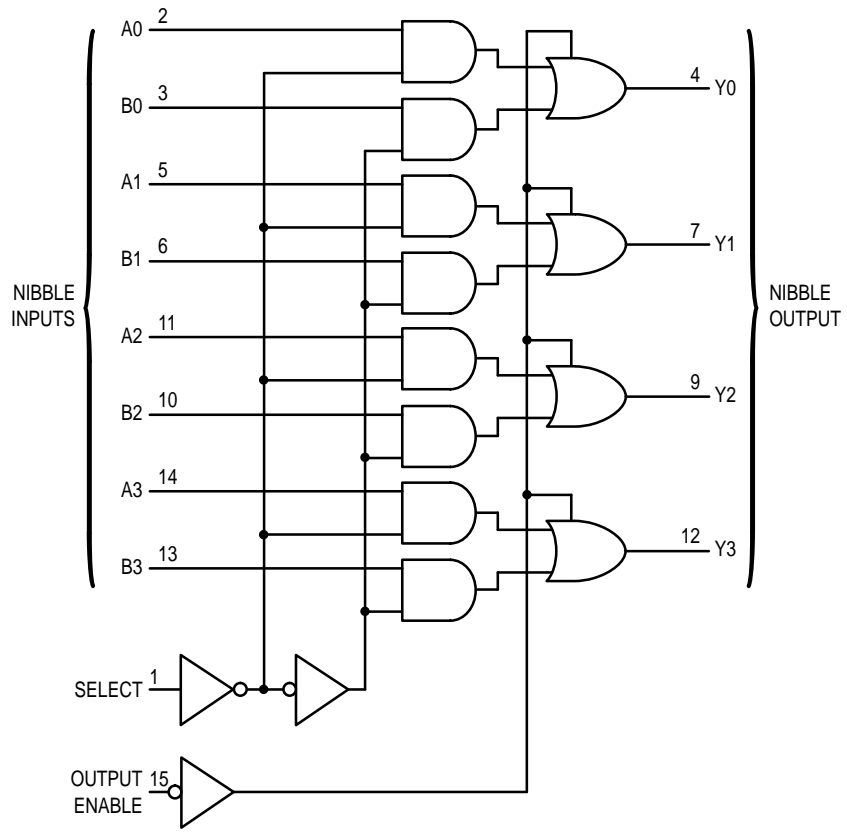
Figure 4.



* Includes all probe and jig capacitance

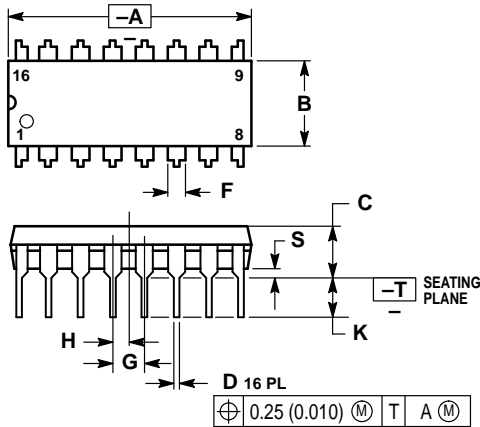
Figure 5.

EXPANDED LOGIC DIAGRAM



OUTLINE DIMENSIONS

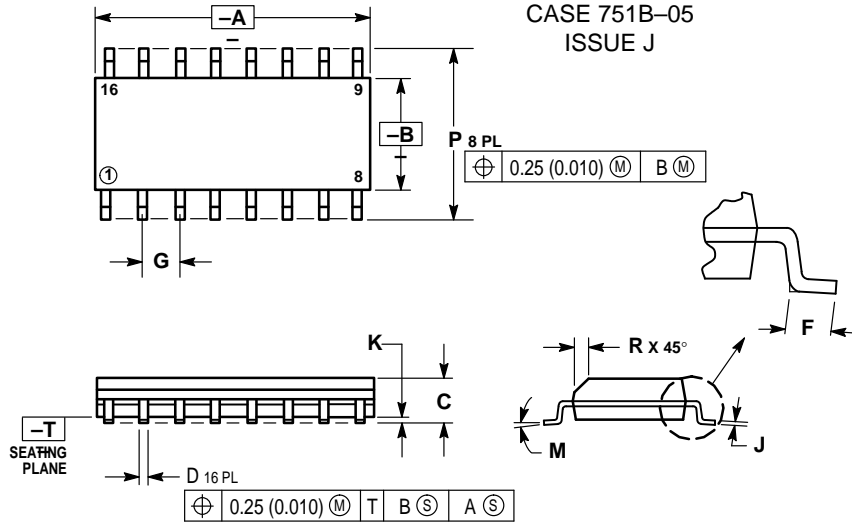
N SUFFIX
PLASTIC PACKAGE
CASE 648-08
ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.070	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B-05
ISSUE J



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

How to reach us:

USA/EUROPE: Motorola Literature Distribution;
 P.O. Box 20912; Phoenix, Arizona 85036. 1-800-441-2447

MFAX: RMFAX0@email.sps.mot.com -TOUCHTONE (602) 244-6609
INTERNET: http://Design-NET.com

JAPAN: Nippon Motorola Ltd.; Tatsumi-SPD-JLDC, Toshikatsu Otsuki,
 6F Seibu-Butsuryu-Center, 3-14-2 Tatsumi Koto-Ku, Tokyo 135, Japan. 03-3521-8315

HONG KONG: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park,
 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852-26629298

